Contents lists available at ScienceDirect

Materials Letters

journal homepage: www.elsevier.com/locate/matlet

White bright luminescence at room temperature from TEOS-based thin films via catalytic chemical vapor deposition



materials letters

A. Dutt ^a, Y. Matsumoto ^{a,b,*}, S. Godavarthi ^b, G. Santana-Rodríguez ^{c,d,1}, J. Santoyo-Salazar ^d, A. Escobosa ^a

^a SEES, Electrical Engineering Department, Centro de Investigación y de Estudios Avanzados del IPN, Mexico City 07360, Mexico

^b Program of Nanoscience and Nanotechnology, Centro de Investigación y de Estudios Avanzados del IPN, Mexico City 07360, Mexico

^c Instituto de Investigaciones en Materiales, Universidad Nacional Autónoma de México, Coyoacán 04510, Mexico

^d Departamento de Física, Centro de Investigación y de Estudios Avanzados del IPN, Mexico City 07360, Mexico

ARTICLE INFO

Article history: Received 16 April 2014 Accepted 30 May 2014 Available online 7 June 2014

Keywords: TEOS Cat-CVD Photoluminescence nc-Si Carbon bonding

ABSTRACT

Strong white luminescence, visible to naked eye at room temperature, was observed from as grown SiO_xC_y thin films without the need of annealing. SiO_xC_y thin films were prepared by using catalytic chemical vapor deposition method (Cat-CVD) employing TEOS solution as the precursor and bubbled with the argon gas to form vapors. TEOS vapors were catalytically decomposed in the deposition chamber with the help of a tungsten filament. Scanning electron microscope (SEM) and transmission electron microscope (TEM) confirmed the formation of nano-crystals in SiO_xC_y matrix. Inter-atomic spacing shows the transition of Si–SiC nano-crystals in matrix. The intense emission is believed to come up either from the carbon incorporation in the nanocrystalline-structured film and/or quantum confinement effect of the observed nano-crystals in SiO_xC_y matrix.

© 2014 Elsevier B.V. All rights reserved.

1. Introduction

Visible luminescence from porous Si was the foremost step related to optical investigation of this material [1]. Following that research, next phase was focused on fabricating nanocrystalline silicon (nc-Si) embedded in silicon oxide (SiO_x) or silicon nitride (SiN_x) matrix using various source gases by other deposition techniques [2-6]. In order to obtain an efficient photoluminescence (PL) response based on confinement effect from these Si based thin films, it is always necessary to anneal the samples [7,8]. This temperature range is quite high for device manufacturing in microelectronics industry. To overcome this restraint, it is desirable to find alternative and safe deposition process related to Si material at lower substrate temperature. Cat-CVD is one of the prospective techniques by offering advantages like efficient use of precursors and no plasma damage compared to other techniques. Basic film properties using TEOS (Si (OC₂H₅)₄) by means of Cat-CVD have been demonstrated previously by Nakayama

E-mail address: ymatsumo@cinvestav.mx (Y. Matsumoto). ¹ In sabbatical stay.

http://dx.doi.org/10.1016/j.matlet.2014.05.206 0167-577X/© 2014 Elsevier B.V. All rights reserved. et al. [9,10] and also there is report of Cat-CVD with TEOS as the precursor for dielectric applications [11]. Some other groups have reported defect induced PL in near infrared region [12,13] using TEOS with other deposition techniques. Also, some authors reported basic characterization and memory device application by means of same precursor [14,15]. In the present job, we fabricated for first time the nano-crystalline phased SiO_xC_y thin films by means of Cat-CVD at relatively low substrate temperature, which shows bright white emission without the need of any post-deposition heat-treatment.

2. Experimental

The Cat-CVD is also known as Hot wire CVD (HW-CVD) and the working operation have been described elsewhere [16]. In this study, TEOS (Sigma-Aldrich 131903- Purity 98%) related Si–O–C films were prepared using built in-house up-stream Cat-CVD equipment. TEOS was bubbled with a constant flow rate of 50 sccm using Ar gas. Both TEOS source and its vapors transportation tubing system to the deposition chamber were maintained at 30 °C using resistive heating element in order to avoid TEOS vapor condensation. Three different depositions by varying filament temperature ($T_{\rm fil}$) were carried out. $T_{\rm fil}$ was maintained at 1700,



^{*} Corresponding author at: SEES, Electrical Engineering Department, Centro de Investigación y de Estudios Avanzados del IPN, Mexico City 07360, Mexico. Tel.: +52 57473800 3783.

1800 and 1900 °C for the depositions on the silicon substrate. Distance from the filament to substrate was kept 5 cm and temperature of substrate (T_{subs}) was maintained at 300 °C for all the three processes. Fourier Transform Infrared (FTIR) spectrum was recorded within the range of 400 to 4000 cm⁻¹ by Thermo-Nicolet-nexus-470. Photoluminescence (PL) spectra were obtained using a Kimmon Koha He–Cd laser with excitation wavelength of 325 nm and output power of 20 mW, at room temperature. Compositional investigations of the samples were carried using Bruker energy dispersive analysis of X-ray (EDX) equipped in Carl Zeiss-AURIGA-FESEM. Bright field images and selected area



Fig. 1. Infrared absorption spectra of the thin film deposited at $T_{\rm sub}{=}300$ °C and $T_{\rm fil}{=}1900$ °C.



Fig. 2. Representative PL spectra of as-deposited film at T_{sub} =300 °C and T_{fil} =1900 °C, with the inset showing camera image of the white emission from sample.

electron diffraction (SAED) were obtained in a TEM JEOL-JEM-2010 at 200 kV.

3. Results and discussion

Intense white luminescence is observed for all the deposited samples. To demonstrate the structural analysis, results related to only one condition with $T_{\rm fil}$ =1900 °C have been illustrated. Fig. 1 shows the Infrared absorption spectra (FTIR spectra) of Si–O–C thin film at $T_{\rm subs}$ =300 °C and $T_{\rm fil}$ =1900 °C.

The spectra, in general, exhibited absorption peaks related to Si–O–Si rocking, Si–C stretching, Si–H bending, Si–OH, Si–O–Si antisymmetric stretching, Si–CH₃ bending T ($\equiv O_3 \equiv Si$ –CH₃), C=C and C–H modes [17–22] and confirms the presence of Si, O and C in the film. Fig. 2 shows a wide PL spectrum from 360 nm to around 710 nm for the same sample.

For more detailed investigation of the morphology and the possible PL mechanism, SEM studies have been carried out. Fig. 3(a) shows a SEM image of the film at $T_{\rm fil}$ =1900 °C and formation of some cluster structures can be observed.

For the compositional analysis of observed clusters and matrix surrounding them, EDX studies have been performed. Fig. 3(b) illustrates the elemental analysis of the thin film using EDX. Relative concentration of Si, O and C confirms the formation of SiO_xC_y type of film.

To verify the type of clusters and to confirm the presence of crystalline phase, TEM study is also illustrated. Fig. 4(a) and (b) shows the bright-field TEM images for the deposited film.

For one of the selected portion in Fig. 4 electron diffraction (SAED) pattern is also shown in the inset. Inter-atomic spacing shows the presence of silicon and silicon carbide nanocrystallinephase in the SiO_xC_y matrix surrounded by amorphous material. Generally, in case of SiO_xC_y or SiO_x :C films deposited by other methods, observed PL is normally attributed to bonding related to C, Carbon related defects (CODCs), neutral oxygen vacancy (NOV) defects or carbon rich silica [18,21,23,24]. In the present work, using low cost and safe precursor instead of gases like SiH4, we reported presence of nano-crystals related to Si and SiC obtained at low temperature without the requirement of annealing process. It should be stated that due to the structural complexity: it is a difficult situation to give any particular interpretation regarding PL mechanism. One of the possible explanation could be the presence of various C related bands at 800 cm⁻¹ (Si–C stretching), 1638 cm^{-1} (C=C) and $2800-3000 \text{ cm}^{-1}$ (C=H). It summarizes that the possible emission levels could be due to the element C or it may be due to the presence of Si-C bonding states [25]. At the same time, we cannot rule out the presence of nanocrystalline phases in the film and another probability is that the



Fig. 3. (a) SEM image of sample deposited at T_{sub} =300 °C and T_{fil} =1900 °C, (b) Elemental analysis of the matrix involving Si, O and C using EDX



Fig. 4. (a) Cross sectional bright-field TEM image of the film deposited at T_{sub} =300 °C and T_{fil} =1900 °C with inset showing SAED pattern for the region highlighted, (b) Bright-field TEM image of one of the selected portion from Fig. 3(a).

nano-crystallites related to Si and SiC are well passivated by –CH3 (1270 cm⁻¹), –OH (960 cm⁻¹) or C groups which could lead to well defined quantum confinement effect. Passivation of nanocrystallites also plays an influential role for enhancing the recombination rate [26]. Further characterizations have to be carried out for understanding the role of carbon as well as nanocrystallineclusters for this bright luminescence. This bright luminescence from TEOS based thin film could open many gateways for optical device fabrication.

4. Conclusions

In conclusion, we have demonstrated safe and low cost deposition technique to obtain bright white luminescence from as-deposited films using TEOS as the precursor without the requirement of any post-deposition temperature treatments. Comparative study of FTIR, SEM and TEM shows formation of silicon and silicon carbide based nano-crystals in a SiO_xC_y matrix. Further studies could help in understanding the PL mechanism. It could open a gateway for optical device related research based on this technology and make this TEOS related material comparable to direct band gap semiconductor materials.

Acknowledgment

The authors thank Angela Gabriela López for sample preparations. The Authors are indebted to Adolfo Tavira Fuentes and Josué E. Romero-Ibarra for their technical assistance. We would express our sincere thanks to Dr. Hiroshi Nakayama, Professor of Osaka City University and the president of Material Design Factory Co. Ltd., who recommended us to use Catalytic-CVD. This project is supported by CONACYT CB2009-128723.

References

- [1] Canham LT. Appl Phys Lett 1990;57:1046-8.
- [2] Smirani R, Martin F, Abel G, Wang YQ, Chicoine M, Ross GG. J Lumin 2005;115:62–8.
- [3] Yang Yang, Xu Ling, Yang Fei, Liu Wenqiang, Xu Jun, Ma Zhongyuan, et al. J Non-Cryst Solids 2010;356:2790–3.
- [4] Wang Li, Ma Zhongyuan, Huang Xinfan, Li Zhifeng, Li Jian, Bao Yun, et al. Solid State Commun 2001;117:239–44.
- [5] Matsumoto Y, Godavarthi S, Ortega M, Sánchez V, Velumani S, Mallick PS. Thin Solid Films 2011;519:4498–501.
- [6] Sanatana G, de melo O, Aguilar- Hernández J, Monroy BM, Fandiño J, Cruz F, et al. Phys. status solidi C 2005;2:3698–701.
- [7] Ma Zhongyuan, Han Peigao, Huang Xinfan, Sui Yanping, Chen San, Qian Bo, et al. Thin Solid Films 2006;515:2322–5.
- [8] Tsai Jen-Hwan. Vacuum 2012;86:1983–7.
- [9] Hata Tsuyoshi, Nakayama Hiroshi. Thin Solid Films 2008;516:558-63.
- [10] Nakayama Hiroshi, Hata Tsuyoshi. Thin Solid Films 2006;501:190-4.
- [11] Takatsuji K, Kawakami M, Makita Y, Murakami K, Nakayama H, Miura Y, et al. Thin Solid Films 2003;430:116–9.
- [12] Lau HW, Tan OK, Liu Y, Ng CY, Chen TP, Pita K, et al. J Appl Phys 2005;97:104037–44.
- 13] Yu Shu, Tu Rong, Ito Akihiko, Goto Takashi. Mater Lett 2010;64:2151-4.
- [14] Lau HW, Tan OK, Liu Y, Ng CY, Chen TP. Nanotechnology 2006;17:4078–81.
- [15] Lau HW, Tan OK. Appl Phys Lett 2006;88:103101-3.
- [16] Matsumoto Y, Reves MA, Escobosa A. J Appl Phys 2005;98:014909-4.
- [17] Seo Se-Young, Cho Kwan-Sik, Shin Jung H. Appl Phys Lett 2004;84:717–9.
- [18] Vasin AV, Okholin PN, Verovsky IN, Nazarov AN, Lysenko VS, Kholostov KI, et al. Semiconductors 2011;45:350-4.
- [19] Vasin AV, Kolesnik SP, Konchits AA, Rusavsky AV, Lysenko VS, Nazarov AN, et al. J Appl Phys 2008;103:123710–7.
- [20] Tolstoy VP, Chernyshova IV, Skryshevsky VA. Handbook of Infrared Spectroscopy of Ultrathin Films. NJ: Wiley; 2003; 416–75.
- [21] Ding Yi, Shirai Hajime. J Appl Phys 2009;105:043515-4.
- [22] Majumdar Abhijit, Das Gobind, Patel Nainesh, Mishra Puneet, Ghose Debabrata, Hippler Rainer. J Electrochem Soc 2008;155:D22-6.
- [23] Gallis Spyros, Nikas Vasileios, Suhag Himani, Huang Mengbing, Kaloyeros Alain E. Appl Phys Lett 2010;97:081905-3.
- [24] Vasin AV, Kushnirenko VI, Verovsky IN, Lysenko VS, Nazarov AN, Ishikawa Yukari, et al. Tech Phys Lett 2009;35:559–62.
- [25] Vasin Andriy, Rusavsky Andriy, Nazarov Alexei, Lysenko Vladimir, Rudko Galyna, Piryatinski Yurii, et al. Phys Status Solidi A 2012;209:1015–21.
- [26] Kusová Katerina, Cibulka Ondrej, Dohnalova Katerina, Pelant Ivan, Valenta Jan, Fucikova Anna, et al. ACS Nano 2010;4:4495–504.